



 MICROCHIP			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			JEDEC 97 Product Marking and/or Pkg. Labeling e4			
Semiconductor Device Type: AIZL (8BX) 010 MSOP 3x3x1.0mm NiPdAu												
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	10.77	(mg) Total	Mold Compound	% of Total Weight	45.08		
Silica, vitreous	60676-86-0	Mold Compound	38.318	9.158	383,180		Silica, vitreous	60676-86-0	85.00			
Epoxy Resin	Trade Secret	Mold Compound	6.672	1.595	66,718		Epoxy Resin	Trade Secret	14.80			
Carbon black	1333-86-4	Mold Compound	0.090	0.022	902		Carbon black	1333-86-4	0.20			
							Total		100.00			
Copper	7440-50-8	Lead Frame	44.464	10.627	444,643	10.95	(mg) Total	Lead Frame	% of Total Weight	45.83		
Iron	7439-89-6	Lead Frame	1.123	0.268	11,228		Copper	7440-50-8	97.02			
Zinc	7440-66-6	Lead Frame	0.160	0.038	1,604		Iron	7439-89-6	2.45			
Phosphorous	7723-14-0	Lead Frame	0.082	0.020	825		Zinc	7440-66-6	0.35			
Silver	7440-22-4	Die Attach	0.585	0.140	5,850		Phosphorous	7723-14-0	0.18			
Diester Resin	94-80-4	Die Attach	0.117	0.028	1,170		Total		100.00			
Functionalized Urethane Resin	72869-86-4	Die Attach	0.039	0.009	390		0.19	(mg) Total	Die Attach		% of Total Weight	0.78
Epoxy Resin	9003-36-5	Die Attach	0.020	0.005	195		Functionalized Urethane Resin	Silver	7440-22-4		75.00	
Epoxy Resin	13561-08-5	Die Attach	0.020	0.005	195	Diester Resin		94-80-4	15.00			
Silicon	7440-21-3	Chip (Die)	5.640	1.348	56,400	Functionalized Urethane Resin		72869-86-4	5.00			
Gold	7440-57-5	Wire Bond	1.930	0.461	19,300	Epoxy Resin		9003-36-5	2.50			
Nickel	7440-02-0	Plating on external leads (pins)	0.666	0.159	6,660	Epoxy Resin		13561-08-5	2.50			
Palladium	7440-05-3	Plating on external leads (pins)	0.037	0.009	370	Total		100.00				
Gold	7440-57-5	Plating on external leads (pins)	0.037	0.009	370	1.35	Total (mg)	Chip (Die)	% of Total Weight	5.64		
			TOTALS:	100.000	23.900	1,000,000	Doped Silicon		7440-21-3	100		
			0.0239 g Total Mass			Total		100.00				
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)												
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.												
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.												
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/												
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.												
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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table												
						0.46	(mg) Total	Wire Bond	% of Total Weight	1.93		
							Gold	7440-57-5	100.00			
							Total		100.00			
						0.18	(mg) Total	Plating on external leads (pins)	% of Total Weight	0.74		
							Nickel	7440-02-0	90.00			
							Palladium	7440-05-3	5.00			
							Gold	7440-57-5	5.00			
						Total		100.00				
						23.90						
										100.00		